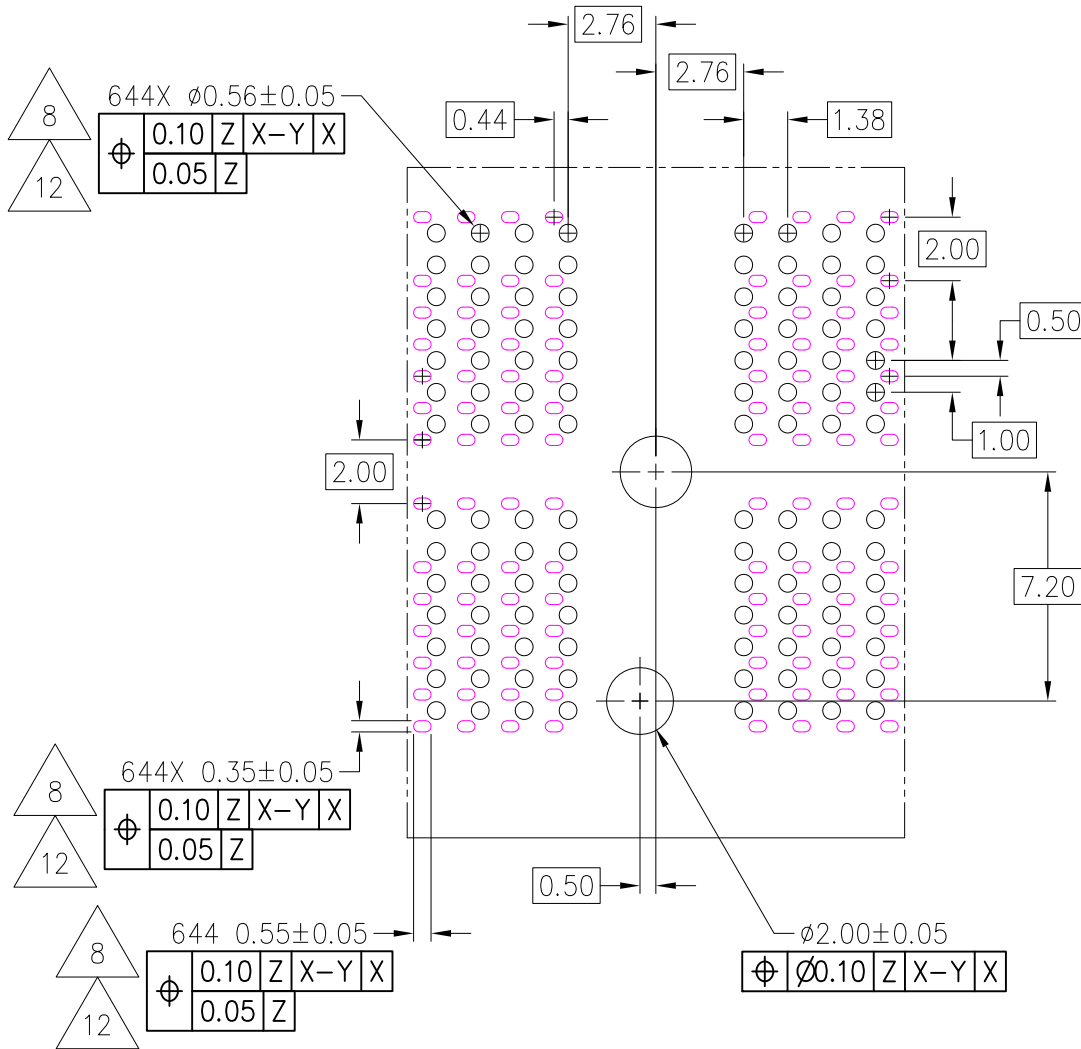
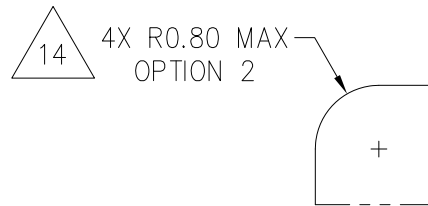
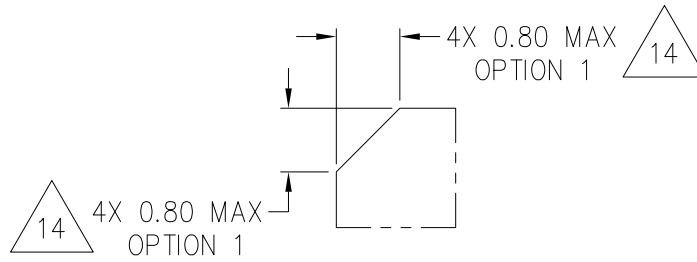


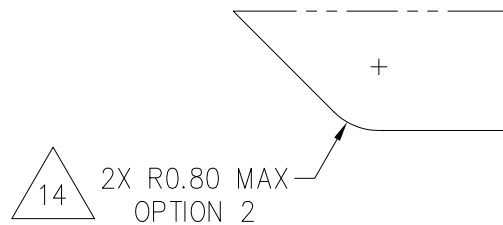
REFERENCE EXPOSED GROUND STRIP (BOTH SIDES)



DETAIL A



DETAIL B

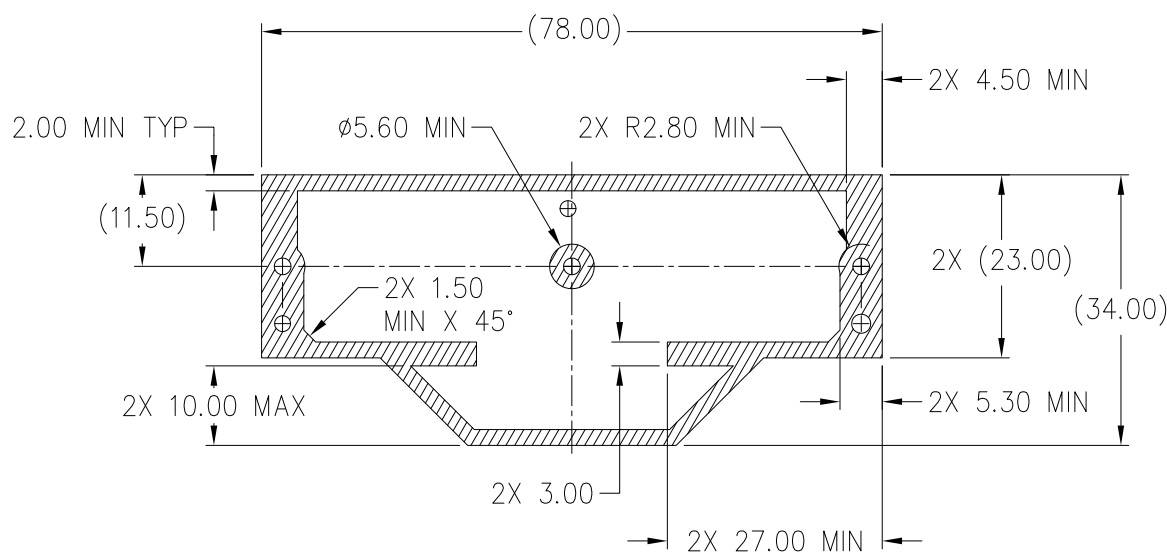


DETAIL C

ANY COMBINATION OF CHAMFER AND RADII CAN BE USED

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009
2. TOLERANCES ON ALL DIMENSIONS  $\pm 0.15$  UNLESS OTHERWISE SPECIFIED
3. ALL DIMENSIONS ARE MM
- 4 DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON THE MODULE
- 5 BORDER OF COMPONENT AREA
- 6 BORDER OF EXPOSED COPPER TOP LAYER FOR MODULE RETENTION
- 7 RESERVED TO ATTACH RFI/EMI SHIELD
- 8 SURFACE TERMINAL (AKA. CONTACT PAD)
- 9 REFER TO JEDEC REGISTERED OUTLINE SO–032 FOR CONNECTOR DIMENSIONS.
- 10 KEEPOUT FOR NON–VSS NET AREAS ON TOP LAYER ARE REQUIRED TO AVOID ANY SHORTING RISK WHEN TOP COVER IS USED FOR RETENTION



11 ONLY APPLY TO THE AREA WITH SURFACE TERMINAL (AKA. CONTACT PAD)

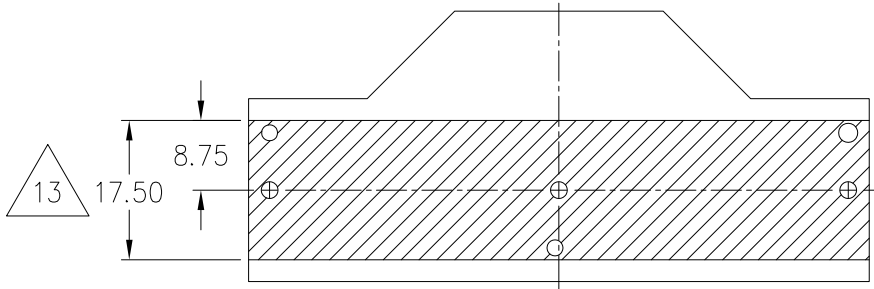
12 PLATING FOR SURFACE TERMINAL (AKA. CONTACT PAD) ARE:

- 1) VARIATION Axxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 0.25 MICROMETERS MINIMUM PALLADIUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
- 2) VARIATION Bxxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.

MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARD EIA 364–1000. RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF TEST CONDITIONS.

13

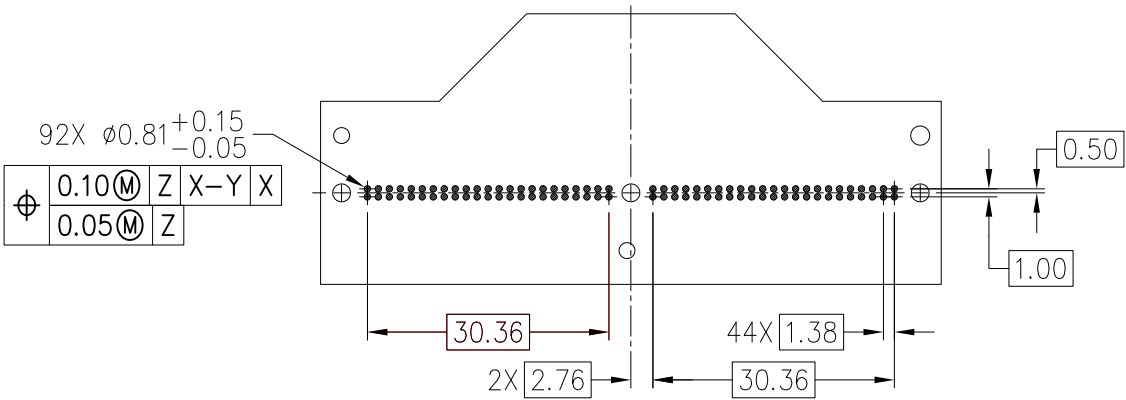
SOLDER MASK IS NOT ALLOWED IN THIS AREA ON THE BOTTOM LAYER, WHERE THE SURFACE TERMINALS (AKA. CONTACT PADS) ARE PRESENT.



14

CHAMFER OR RADIUS IS OPTIONAL.

15. VOID METAL WITHIN AREA OF  $\phi 0.81$  CIRCLES ON THE BOTTOM LAYER WHERE CONNECTOR TERMINALS COULD BE PRESENT.



STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO-357A_XBMA-H644_I1p0_R78p0x23p0Z2p6	AUG 2023	14-219

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SAMSUNG SEMICONDUCTOR  
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SK HYNIX INC.  
SMART MODULAR TECHNOLOGIES INC.  
TE CONNECTIVITY  
WLCO SHENZHEN CO., LTD.

# CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: AUGUST 2023	ITEM NUMBER: 14-219
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CHANGE RECORD HISTORY:
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ISSUE: B	DATE: MARCH 2024	ITEM NUMBER: 14-223
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LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 1		ADD DETAIL B AND C
		ADD NOTE 11
SHEET 2		ADD NOTE 12
SHEET 3		NEW SHEET FOR DETAIL B & C
SHEETS 4 & 5		ADD NOTES 11, 12, 13, AND 14

ISSUE: C	DATE: JUNE 2024	ITEM NUMBER: 14-228
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LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 1	13.10; 26.20	13.10 TSC; 26.20 TSC
SHEET 2	5.52 BASIC	REMOVE DIMENSION: BASIC 5.52
		ADD DIMENSION: BASIC 2.76
SHEET 5		ADD NOTE 15